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(54) Title: ELECTRICAL CONTACT

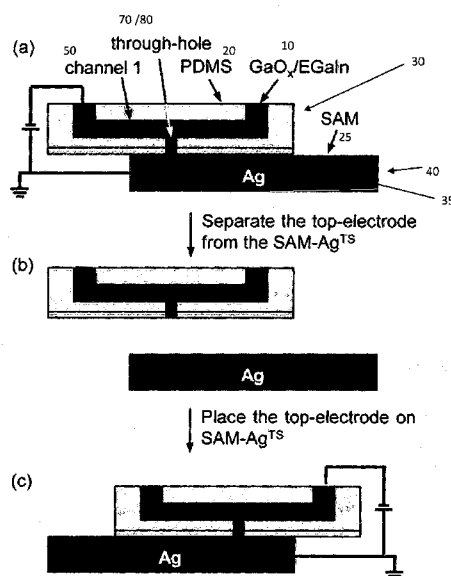


Figure 5

(57) **Abstract:** The present invention relates to an electrical contact. In particular, it relates to an electrical contact capable of establishing an electrical contact with a soft material. More particular, the electrical contact comprises (a) a non-Newtonian liquid metal alloy, the non-Newtonian liquid metal alloy is formed in a polymer insulator, wherein the contact surface of the electrical contact that contacts the soft material is a smooth flat non-patterned surface, the surface comprising the non-Newtonian liquid metal alloy sandwiched between the polymer insulator. The microfluidic device comprising the electrical contact and a method for forming the electrical contact are also disclosed.



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— *with international search report (Art. 21(3))*

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